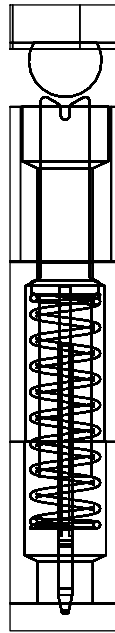
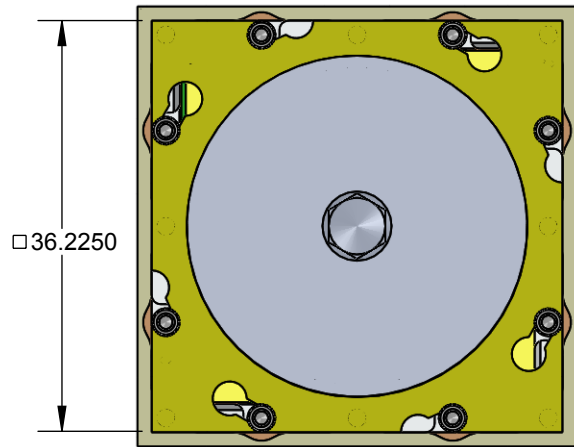


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

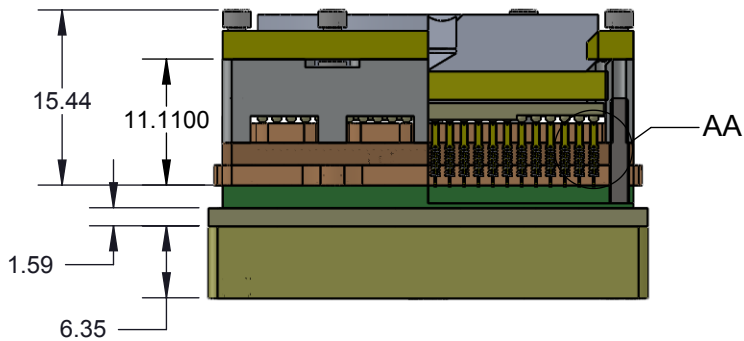
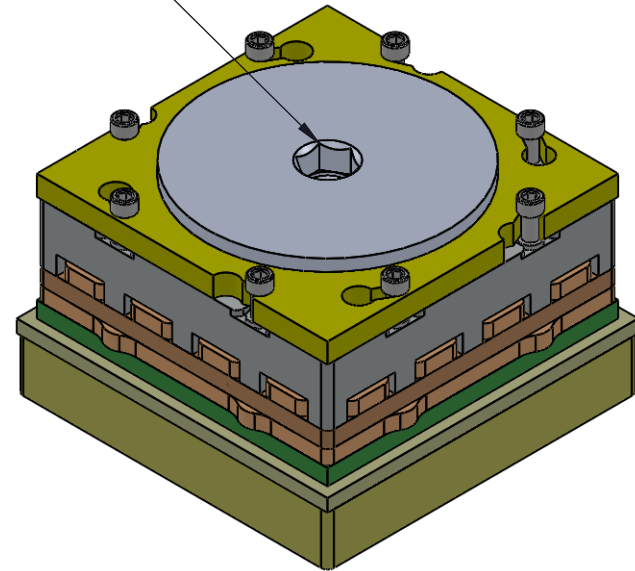


DETAIL AA
SCALE 12 : 1

Features

- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time


Recommended Torque 8 in-lb/ 90.4 N-cm

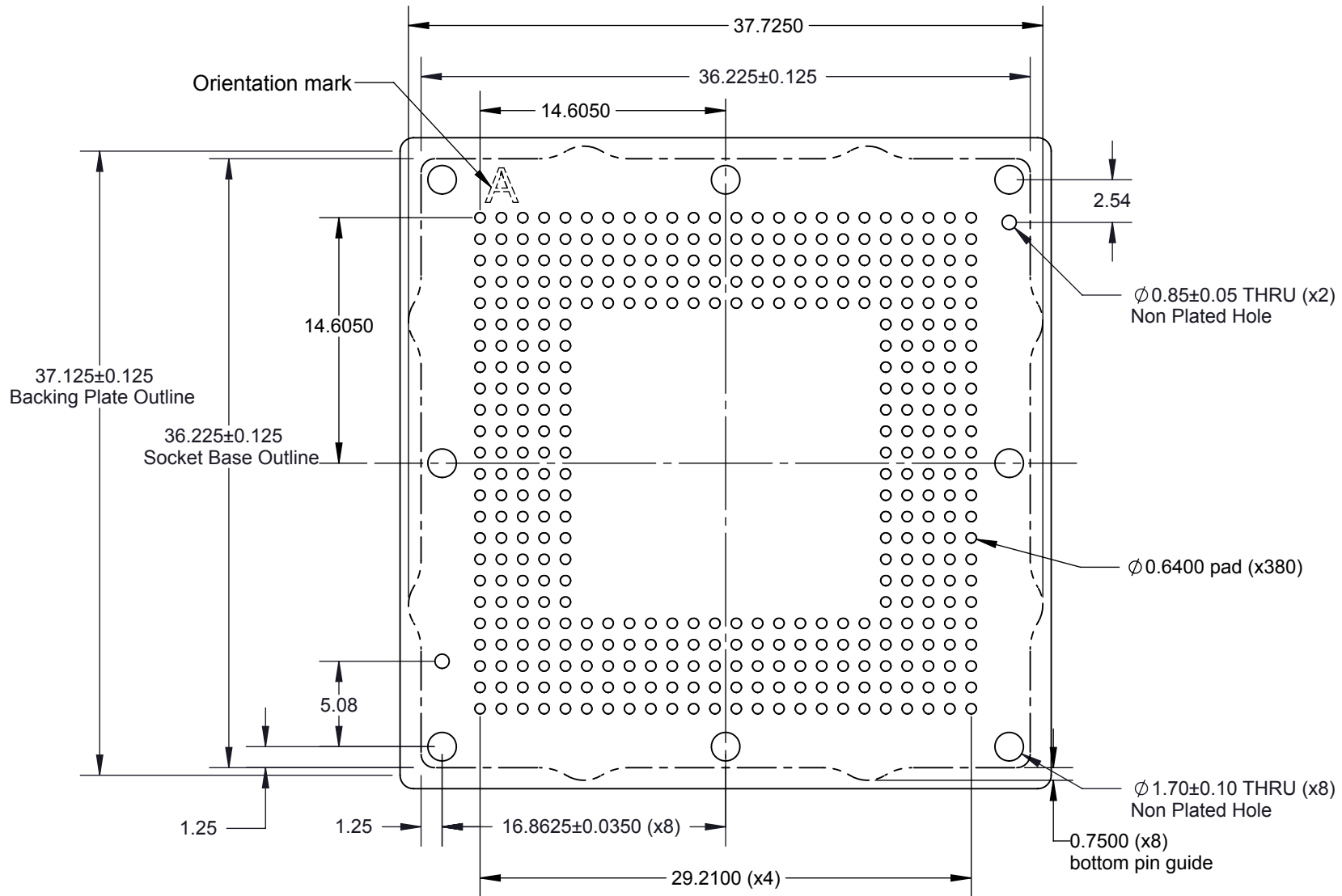


Description: SBT-BGA 31x31mm 24x24 array 1.27mm pitch BGA380

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6039 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: N/A Weight: 69.77	STATUS: Released	SHEET: 1 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 1.5:1
		FILE: SBT-BGA-6039 Dwg	DATE: 8/4/2015	



Target PCB Recommendations

Total thickness: 1.6mm min.


Plating: Gold or Solder finish

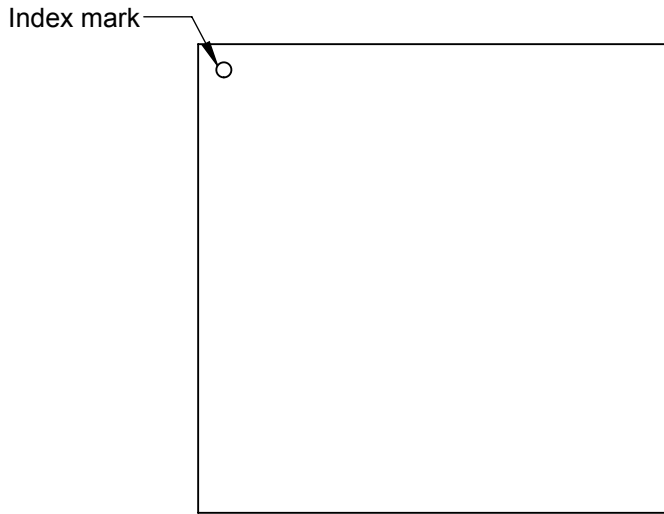
PCB Pad height: Same or higher than solder mask

Description: Recommended Layout

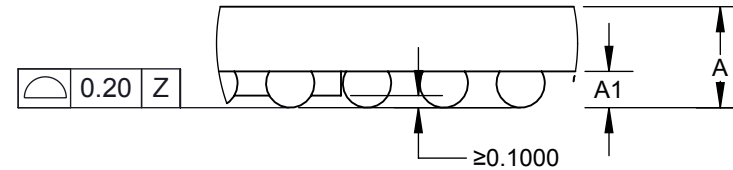
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

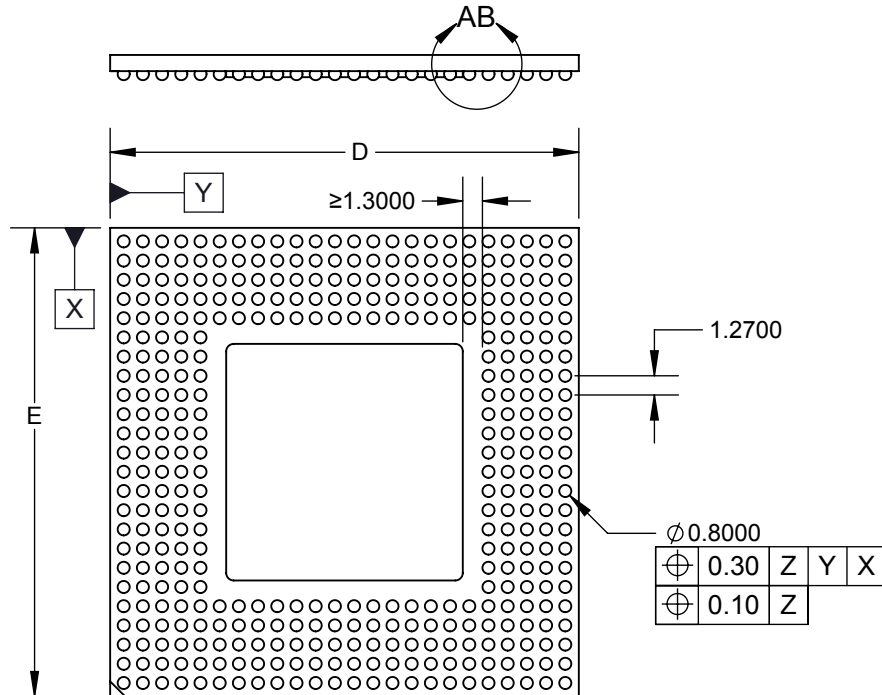
 SBT-BGA-6039 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: N/A Weight: 69.77	STATUS: Released	SHEET: 2 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 2.75:1
		FILE: SBT-BGA-6039 Dwg	DATE: 8/4/2015	



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.



DETAIL AB
SCALE 8 : 1



DIM	Minimum	Maximum
A		1.87
A1	0.5	0.7
b	0.7	0.9
e	1.27	
D	30.8	31.2
E	30.8	31.2


24x24 array

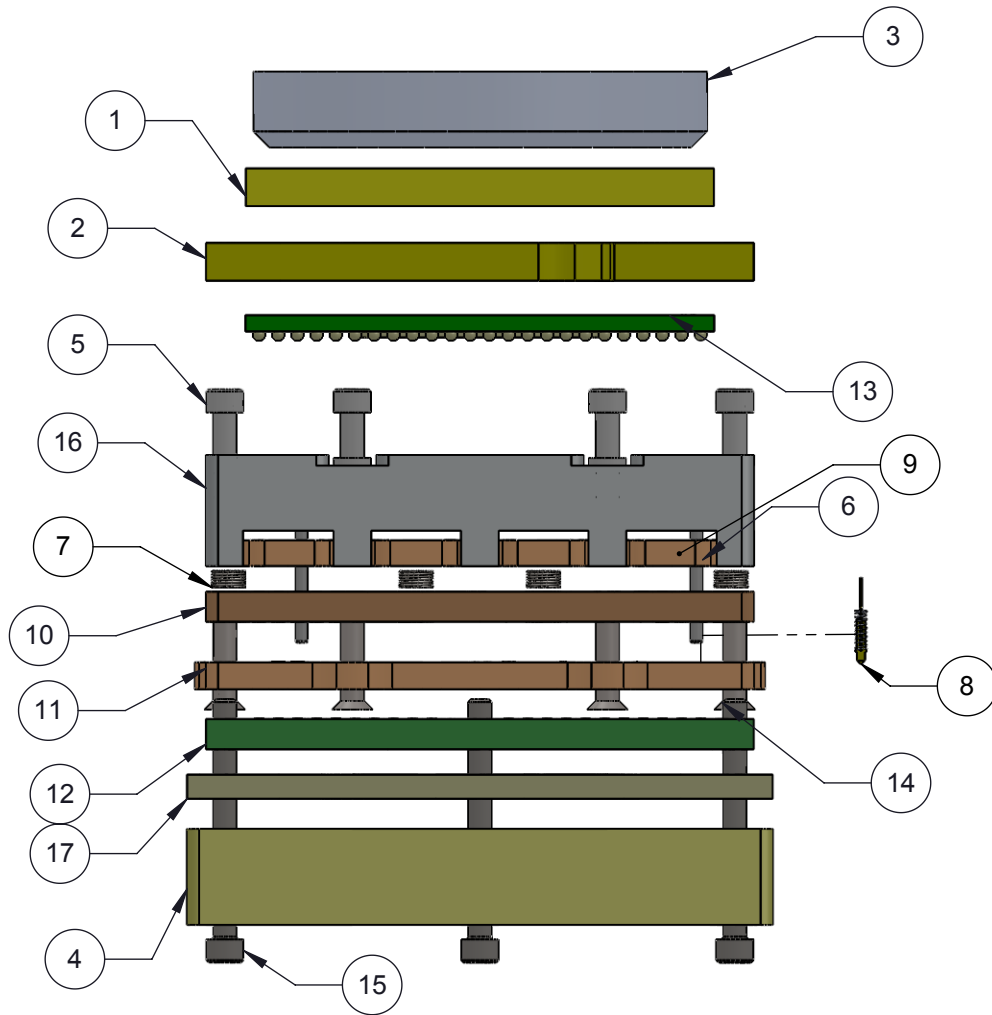
Ironwood package code: BGA380A

Description: BGA Spec

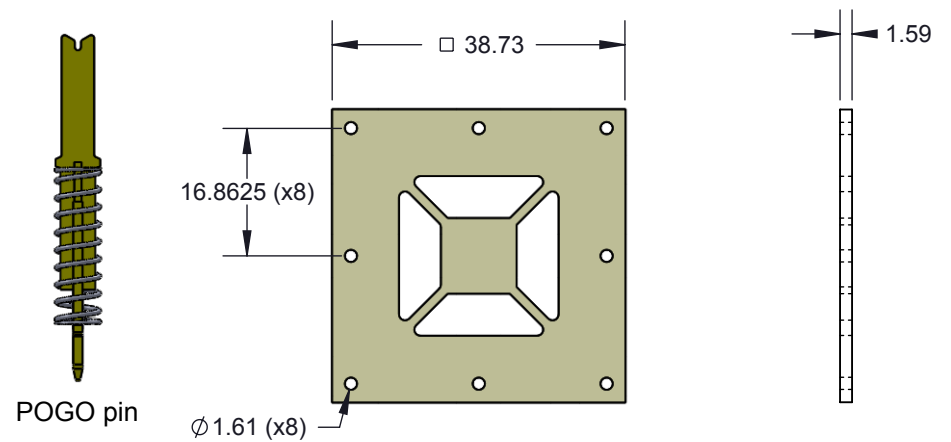
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6039 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: N/A Weight: 69.77	STATUS: Released	SHEET: 3 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 2:1
		FILE: SBT-BGA-6039 Dwg	DATE: 8/4/2015	



ITEM NO.	DESCRIPTION	Material
1	Compression Plate 31mm Ni plated	7075-T6 Aluminum Alloy
2	Socket Lid 31mm swivel Ni plt	7075-T6 Aluminum Alloy
3	Compression Screw, M30	7075-T6 Aluminum Alloy
4	SBT NI PLT BACKING PLT 31MM	7075-T6 Aluminum Alloy
5	#0-80 Shoulder Screw, 1.59mm thread length	Stainless Steel (303)
6	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel
7	Floating Guide Spring	Alloy Steel (SS)
8	Pogo Pin, 1mm Pitch SBT BGA pin	
9	Floating Guide 31mm 1.27mm pitch 24x24 array 380 BGA	Semitron MDS 100
10	Middle Guide 31mm 1.27mm pitch 24x24 array 380 BGA	Semitron MDS 100
11	Bottom Guide 31mm 24x24 array, 1.27mm pitch 380 BGA	Semitron MDS 100
12	PCB BGA380 24x24 array 1.27mm	FR4 High temp
13	Customer's BGA IC 31mm 1.27mm pitch 24x24 array 380 BGA	FR4 Standard
14	#0-80X0.25", 90 deg., head pin guide screw, Peek material	PEEK unfilled
15	#0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Stainless Steel (18-8)
16	Socket Base 31mm IC	7075-T6 Aluminum Alloy
17	Insulation Plate	High Temp FR4




Description: Skt Assem, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

INSULATION PLATE DETAIL

SCALE 1:1

 SBT-BGA-6039 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified>	STATUS: Released	SHEET: 4 OF 4	REV. A	
	Finish: N/A	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 2:1	
	Weight: 69.77	FILE: SBT-BGA-6039 Dwg	DATE: 8/4/2015		